

ABSTRACT

1 The invention provides a bonding structure with compliant bumps, and also includes
2 a stopper structure and a protection layer. Compliant bumps include at least a polymer
3 bump, a metal layer and a surface conductive layer. Both the stopper structure and
4 protection layer are formed with polymer bumps and metal layer. Compliant bumps
5 provide bonding pad and conductive channel. Stoppers are used to prevent compliant
6 bumps from crushing for overpressure in bonding process. The protection layer provides
7 functions of grounding and shielding. The stoppers can be outside or connected with the
8 compliant bumps. The protection layer is lower than the stopper structure and compliant
9 bumps. It can be separated or connected with stoppers.